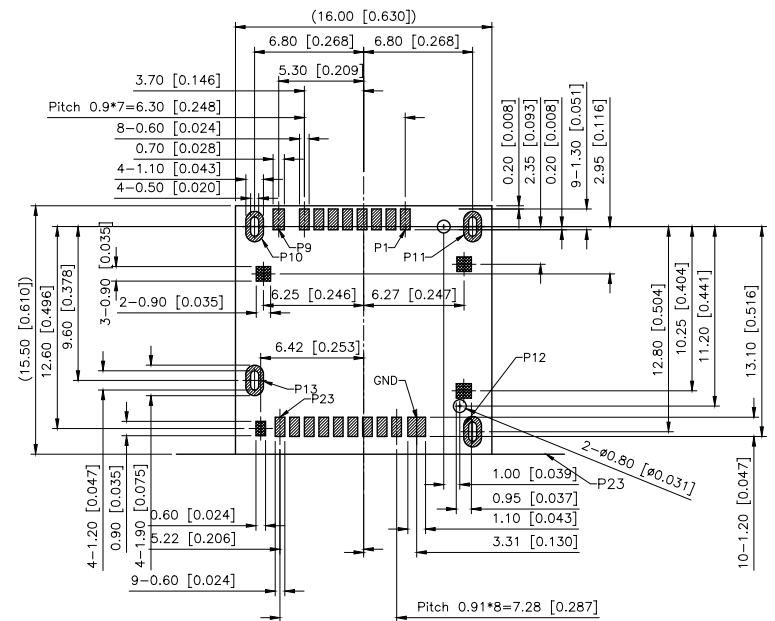
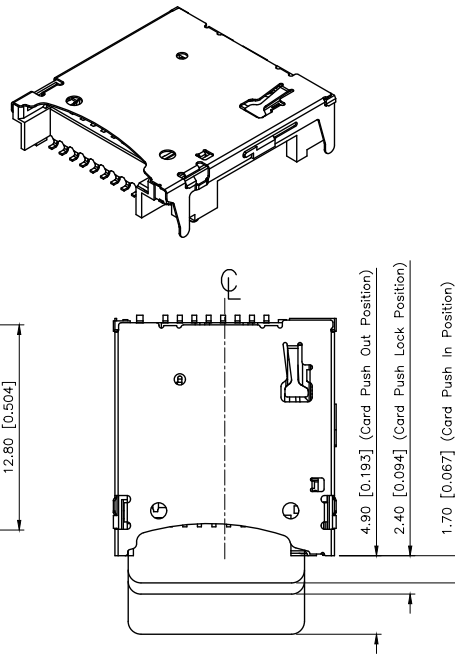
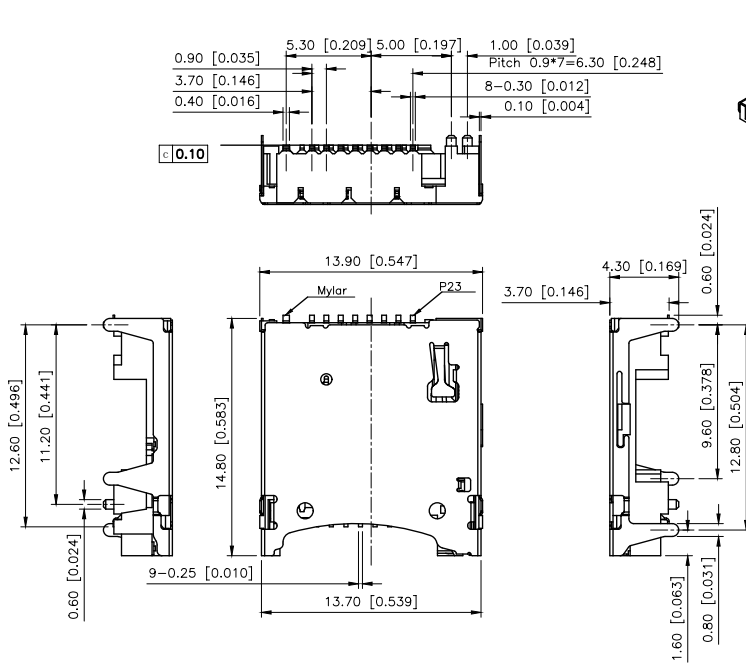


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.16	阿树



Recommended PCB Layout
Top View (Tolerance±0.05)

- Pad Area
Other Component Keepout Area
Red Gluing Area

Note:

- 1.材料 Material
1-1.塑料: LCP, S470, Black, UL94V-0
1-2.触点 Contact: C5210-H
1-3.外壳 Shell: SUS304-H
2.电镀 Plating:
2-1.触点 Contact:
接触电阻 Contact Area: Au 1u" min. Plating Over Ni 50u" min.
焊尾 Solder tails: Gold Flash Plating Over Ni 50u" min.
2-2.外壳 Shell:
Solderability Ni 50u" min. Over All
3. Contact And Tail Coplanarity To Be 0.10mm max.

Pin No.	Pin Assignment
P1	Micro SD DAT2
P2	Micro SD CD/DAT3
P3	Micro SD CMD
P4	Micro SD VDD1
P5	Micro SD CLK
P6	Micro SD VSS
P7	Micro SD DAT0/RCLK+
P8	Micro SD DAT1/RCLK-
P9	Micro SD CD
P10	GND
P11	GND
P12	GND
P13	GND
P14	GND
P15	Micro SD VDD2
P16	Micro SD SWIO
P17	Micro SD VSS
P18	Micro SD D0+
P19	Micro SD D0-
P20	Micro SD VSS
P21	Micro SD D1-
P22	Micro SD D1+
P23	Micro SD VSS

Card Uninsertion	Open
Card Half Insertion	Open
Card Insertion	Close
Open	Close
P6	P9
P6	P9

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE:
CHECKED		UNIT: mm/in	PART NO.:
APPROVED		SIZE: A4	DWG NO.:
			X-KTTF-1150-11
		SCALE	PAGE
		N/A	1/1
		REVISION	A1